

Assembly Transfer of Select 10x10 and 14x14 TQFP_EP Products to Amkor Philippines

Automotive 10x10 TQFP_EP Using G700L/3230 at Amkor Philippines

QUALIFICATION PLAN / STATUS			
TEST	SPECIFICATION	SAMPLE SIZE	EXPECTED COMPLETION DATE
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 45	March 2015
Autoclave (AC)*	JEDEC <i>JESD22-A102</i>	3 x 45	March 2015
Highly Accelerated Stress Test (HAST)*	JEDEC <i>JESD22-A110</i>	3 x 45	March 2015
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	3 x 11	March 2015
High Temperature Storage Life (HTSL)	JEDEC <i>JESD22-A103</i>	1 x 45	March 2015

* These samples will be subjected to preconditioning (per J-STD-020 Level 3) prior to the start of the stress test. Level 3 preconditioning consists of the following: 1. Bake – 24 hours at 125°C; 2. Soak – unbiased soak for 192 hours at 30°C, 60%RH; 3. Reflow – three passes through a reflow oven with a peak temperature of 260°C. TC samples will be subjected to wire-pull test after 500 cycles.

Automotive 14x14 TQFP_EP Using G631HQ/3230 at Amkor Philippines

QUALIFICATION PLAN / STATUS			
TEST	SPECIFICATION	SAMPLE SIZE	EXPECTED COMPLETION DATE
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 45	April 2015
Autoclave (AC)*	JEDEC <i>JESD22-A102</i>	3 x 45	April 2015
Highly Accelerated Stress Test (HAST)*	JEDEC <i>JESD22-A110</i>	3 x 45	April 2015
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	3 x 11	April 2015
High Temperature Storage Life (HTSL)	JEDEC <i>JESD22-A103</i>	1 x 45	April 2015

* These samples will be subjected to preconditioning (per J-STD-020 Level 3) prior to the start of the stress test. Level 3 preconditioning consists of the following: 1. Bake – 24 hours at 125°C; 2. Soak – unbiased soak for 192 hours at 30°C, 60%RH; 3. Reflow – three passes through a reflow oven with a peak temperature of 260°C. TC samples will be subjected to wire-pull test after 500 cycles

TQFP_EP_10x10_14x14_Part_List_Rev_A

FG Model	Pkg Type	Body Size	PkgLead Count	WIRE DIA. (BEFORE)	WIRE DIA. (AFTER)	EPOXY (BEFORE)	EPOXY (AFTER)	MOLD (BEFORE)	MOLD (AFTER)	MOLD GATE POSITION (BEFORE)	MOLD GATE POSITION (AFTER)
AD8284WCSVZ-RL	TQFP_EP	10X10X1.0	64	1	1	3230	3230	G700L	G700L	Pkg Corner	Pkg Corner
ADAU1442YSVZ-3A	TQFP_EP	14X14X1.0	100	1	1	3230	3230	G700L	G631HQ	Pkg Corner	Package top side, opposite corner of Pin 1 mark
ADW80001YSVZ	TQFP_EP	14X14X1.0	100	1	1	3230	3230	G700L	G631HQ	Pkg Corner	Package top side, opposite corner of Pin 1 mark
ADW80001YSVZ-RL	TQFP_EP	14X14X1.0	100	1	1	3230	3230	G700L	G631HQ	Pkg Corner	Package top side, opposite corner of Pin 1 mark
ADW80009BSVZ	TQFP_EP	14X14X1.0	100	1	1	3230	3230	G700L	G631HQ	Pkg Corner	Package top side, opposite corner of Pin 1 mark
ADW80000YSVZ	TQFP_EP	14X14X1.0	100	1	1	3230	3230	G700L	G631HQ	Pkg Corner	Package top side, opposite corner of Pin 1 mark
ADW80000YSVZ-RL	TQFP_EP	14X14X1.0	100	1	1	3230	3230	G700L	G631HQ	Pkg Corner	Package top side, opposite corner of Pin 1 mark